REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A3			Modify some detail	05/13'26	Paul

CUSTOMER DRAWING

RoHS Compliant

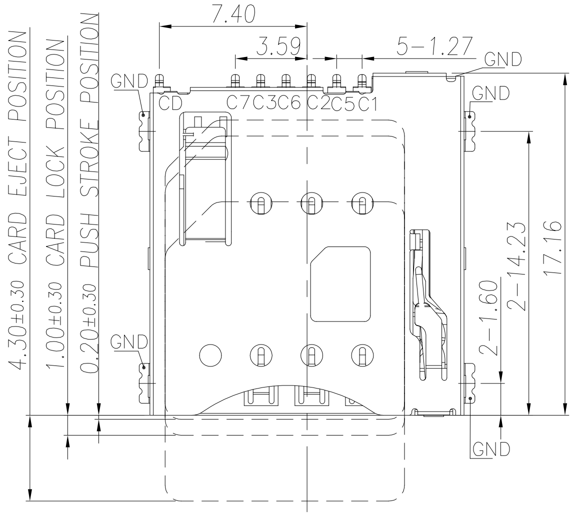
ORDERING INFORMATION

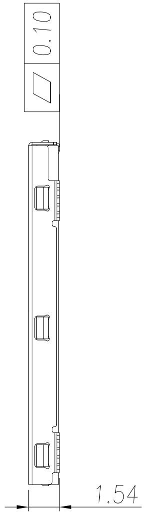
SMPI - S07 (XX T)
1 2 3

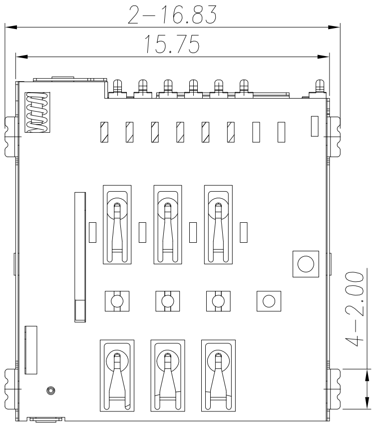
1 *PRODUCT SERIES:*
Micro-SIM CARD SOCKET
PUSH-PUSH TYPE.

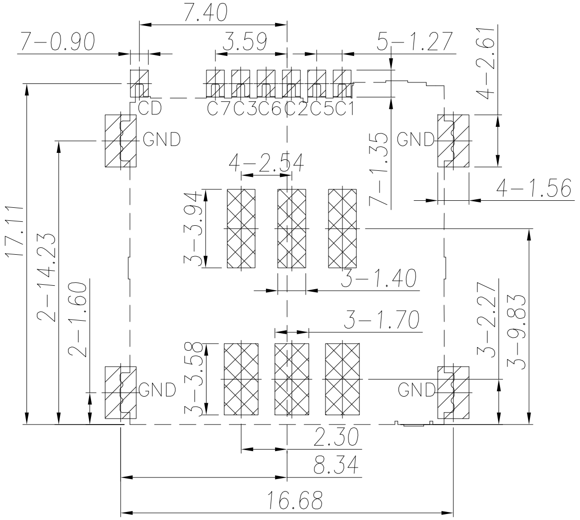
2 *ITEM NO.:*
6PIN, 1.50mm Height.

3 *GOLD PLATING:*
01: G/F.





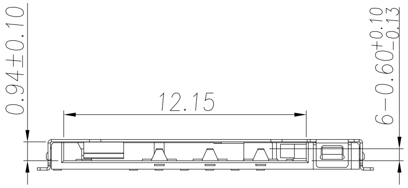


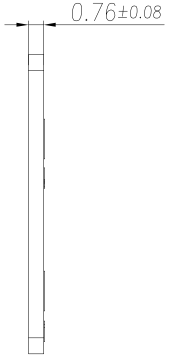


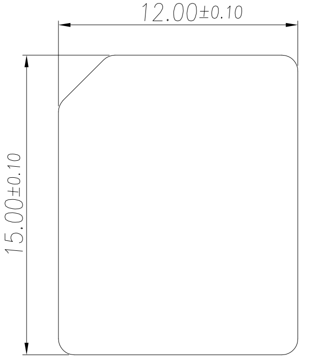
▨ SMT SOLDER AREA ▩ COPPER RESTRICTED AREA
1.TOUCH AREA OF CONTACT
TIPS NO ELECTRICAL FUNCTION
2.NO FIRST PCB_LAYOUT
CIRCUITS IN THE AREA

RECOMMENDED PCB LAYOUT

TOLERANCE:±0.05







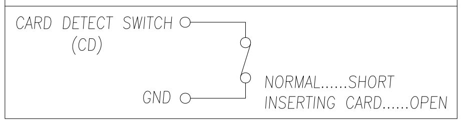
NOTES:

1)MATERIAL:
HOUSING: HIGH-TEMP, LCP, UL 94V-0.
CONTACT: COPPER ALLOY.
SHELL: STAINLESS STEEL.

2)FINISH:
CONTACT:GOLD OVER NICKEL ON CONTACT AREA.
SHELL: GOLD FLASH PLATED ON SOLDER TAILS.

PIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
CD	Detect Switch
C5	GND
C6	VPP
C7	I/O

CRICUIT DIAGRAM FOR CARD DETECT SWITCH



DIM	TOL
X.X	±0.30
X.XX	±0.20
X.XXX	±0.10

SUNFUN

SUNFUN TECHNOLOGY LTD

DRAW NO.	SMPI-S07(A3)	DATE	MATERIAL: SEE NOTES	DRAW NAME: *Micro-SIM Card Socket Push-Push Type, 6Pin 1.50mm Height*
DESIGN:	Paul	05/13'26	FINISH: SEE NOTES	
CHECK:	Paul	05/13'26	FILE: SMPI-S07(A3)	MODEL: MICRO-SIM PP CONN
REVIEW:	Jim	05/13'26	P/N: SMPI-S07(XXT)	UNIT: mm / SHEET: 1/1
APPROVED	Jim	05/13'26	REV. A3 / SCALE	